

PRODUCT

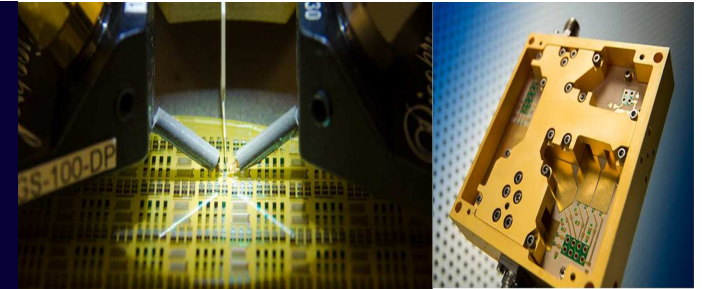
Semiconductor Foundry Services; Assembly and Packaging

Semiconductor Wafer Fabrication & Assembly:

- Advanced Materials such as GaN
- Non-Silicon Wafers (SiC, Diamond)

LMJ used for:

- Wafer Dicing
- Device Singulation



CHALLENGE

Advanced Die Singulation (Wafer dicing)

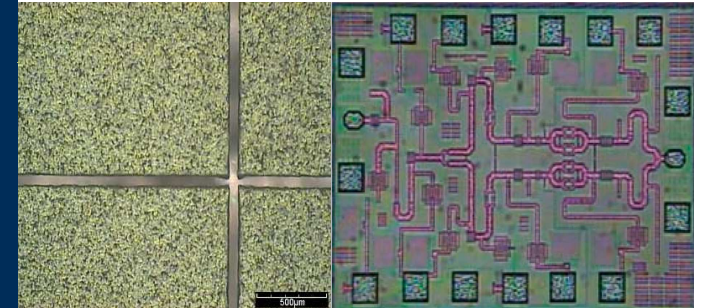
High-Quality wafer dicing

Main processing criteria:

- Small kerf dicing
- No chipping
- Contamination-free

Machining technologies able to reach these criteria:

- Standard Dicing Saw
- Laser MicroJet (LMJ) - water jet guided laser technology with breakthrough sensing



SOLUTION

No heat-related stress, contactless

LMJ advantages versus Dicing Saw:

- Eliminates the high operational costs for blades
- High quality
- High stability

Installed machine type:

- 1 x LDS 300
- 100 W green laser

